

BB02-RG :-2.0mm x 2.0mm (0.079" x 0.79") SOCKET, STRAIGHT, SMD, DUAL ROW - 04 to 80 CONTACTS LOW PROFILE:2.2mm, DUAL ENTRY

SPECIFICATIONS

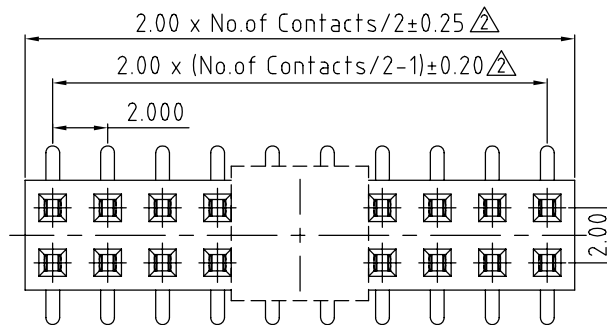
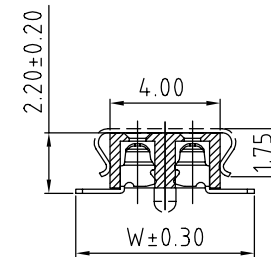
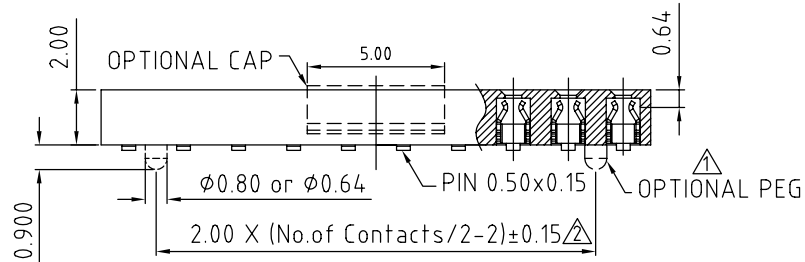
CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACT RESISTANCE	20m ohms MAX.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPREATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: NYLON 6T
PLATING	GOLD OR TIN OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

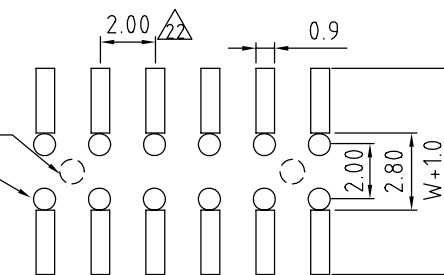
1. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 1.5MM. Δ

MATES WITH:

BB02-FA	BB02-FS	BB02-RN
BB02-FD	BB02-FU	
BB02-FE	BB02-FW	
BB02-FG	BB02-FY	
BB02-FP	BB02-FZ	
BB02-FQ	BB02-RH	

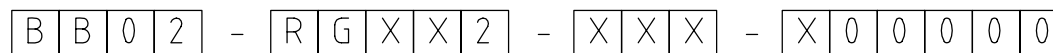


ϕ 1.00 for Peg ϕ 0.80
 ϕ 0.84 for Peg ϕ 0.64
 ϕ 0.80 REF.



BOTTOM ENTRY TYPE
 RECOMMENDED PC BOARD LAYOUT
 (TOLERANCE:±0.05)

HOW TO ORDER



NO. OF CONTACTS
 Δ 04 TO 80
 (MIN. 06 FOR W/PEG)

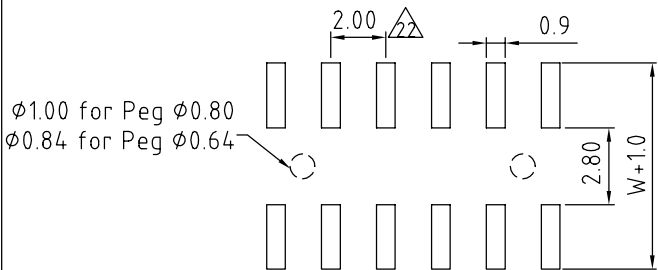
Δ FOOTPRINT
 "W" OPTION
 0 = 6.5MM
 A = 5.3MM

PACKAGING OPTIONS
 3 - TUBE
 Δ 4 - TUBE & FILM
 5 - TUBE & CAP
 6 - T & R
 Δ 7 - T & R & FILM
 8 - T & R & CAP

Δ LOCATING PEG OPTION
 A = WITH PEG ϕ 0.80
 B = WITHOUT PEG
 Δ C = WITH PEG ϕ 0.64

CONTACT PLATING OPTIONS Δ Δ Δ

K = GOLD FLASH (STANDARD)
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 T = BRIGHT TIN
 M = MATT TIN



TOP ENTRY TYPE
 RECOMMENDED PC BOARD LAYOUT
 Δ (TOLERANCE:±0.05)

REV. DATE & DEN
10. 12/05/06 - NYW RELEASE
11. 30/05/06 - NYW
Δ ADD P&K OPTION 4 & 7.
Δ ADD PEG OPTION
MIN. CONTACT NO 06=04.
12. 06/06/06 - NYW
Δ AMEND DIMENSIONS.
13. 08/08/06 - NYW
DRAWING MODIFICATION.
14. 02/10/06 - CHC
Δ REMOVE SELECTIVE GOLD
15. 31/05/07 - NYW
Δ ADD FOOTPRINT W OPTION.
16. 25/07/07 - CHC
Δ ADD SELECTIVE GOLD
17. 16/10/07 - CHC
Δ REMOVE SELECTIVE GOLD
Δ CONTACT PLATING.
18. 18/07/08 - NYW
PLATING MODIFICATION.
19. 04/03/08 - CHC
Δ ADD PEG OPTION C.
20. 10/03/08 - CHC
Δ ADD TOLERANCE OF PCB LAYOUT.
21. 31/12/08 - NYW
DRAWING MODIFICATION.
22. 23/03/10 - NYW
Δ AMEND PEG LAYOUT.

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 .XXX ± 0.10	Material SEE NOTE
Drawn: CHC			NOT TO SCALE
App'd: XXXX	Title SOCKET		
Date: 23 MAR '10	Revision: 2.2		Unit: mm

www.gradconn.com

THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT

Type: BB02-RG
BB02-RG
Drawing Number:
Sheet 1 of 1
Drawing © E and OE